DFW

Patent

Docket No.: NVID-P001125

Information Disclosure Statement Transmittal

I hereby certify that this transmittal of the below described document is being deposited with the United States Postal Service in an envelope bearing First Class Postage and addressed to the Commissioner of Patents, P. O. Box 1450, Alexandria, VA 22313-1450, on the below date of deposit.					
Date of Deposit:	8/12/05	Name of Person Making the Deposit:	Luz Castillo	Signature of the Person Making the Deposit:	Luz Castillo

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): Schieck et al. Confirmation No.: 7655

Application No.: 10/789,637 Group Art Unit: 2812

Filed: February 27, 2004 Examiner: Not yet assigned.

Title: A FLIP CHIP SEMICONDUCTOR DIE INTERNAL SIGNAL ACCESS SYSTEM AND METHOD

Commissioner of Patents
P. O. Box 1450
Alexandria, VA 22313-1450
Sir:

Information Disclosure Statement Transmittal

Transmitted herewith is the following:

_____ Formal drawings, totaling _____ sheets.
_____ Informal drawings, totaling _____ sheets.
X Certification for PTO Consideration
X Information Disclosure statement (2 sheets)
_____ Information Disclosure statement and late filing fee
X Form 1449
_____ Petition for Extension of Time
_____ Other: _____

Fee Calculation (for other than a small entity)					
Fee Items				Fee Rate	Total
Petition for Extension of Time (fee calculated elsewhere				$ .00	
Information Disclosure Statement, late filing				$180.00	
Other:					
Total Fees					0.00

PAYMENT OF FEES

1. The full fee due in connection with this communication is provided as follows:

[ ] The Commissioner is hereby authorized to charge any additional fees associated with this communication or credit any overpayment to Deposit Account No.: 23-0085 .
A duplicate copy of this authorization is enclosed.

[ ] A check in the amount of $

[X] Charge any fees required or credit any overpayments associated with this filing to Deposit Account No.: 23-0085.

kgr 7/98

Please direct all correspondence concerning the above-identified application to the following address:

WAGNER, MURABITO & HAO LLP
Two North Market Street, Third Floor
San Jose, California 95113
(408) 938-9060
Customer No: 000041066

Respectfully submitted,

Date: Aug 5, 2005

By: _____
Anthony C. Murabito
Reg. No. 35,295

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Docket No.: NVID-P001125

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450
Sir:

Certification for PTO Consideration of an Information Disclosure Statement
(Under 37 CFR §1.97)

Consideration of the enclosed Information Disclosure Statement is requested.

1. This certification is being made for this information disclosure statement
   [X] accompanying this certification
   [ ] Filed _____

2. I hereby certify that:

X Each item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the statement.

_____ No item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart application, or, to the knowledge of the person signing certification after making reasonable inquiry, was known to any individual designated in §1.56(c) more than three months prior to the filing of the statement.

3. The person making this certification is

[x] a person who is substantively involved in the preparation or prosecution of the application, and who is associated with the inventor, with the assignee, or with anyone to whom there is an obligation to assign the application (37 C.F.R. 1.56 (c)) and who signs below.

[ ] the inventor(s) who signs below

[ ] the practitioner who signs below on the basis of the information:
   [ ] supplied by the inventors
   [ ] supplied by an individual designated in § 1.56(c)
   [ ] in the practitioners file

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Attorney Docket No.: NVID-P001125

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Commissioner of Patents
P. O. Box 1450
Alexandria, VA 22313-1450

Sir:

Information Disclosure Statement Submitted Pursuant to 37 C.F.R. 1.97(b)

The citations referenced herein, copies attached, may be material to the examination of the above-identified application and are, therefore, submitted in compliance with the duty of disclosure as defined in 37 C.F.R. 1.56. The Examiner is requested to make these citations of official record in the application.

This Information Disclosure Statement submitted in accordance with 37 C.F.R. 1.97(b) is not to be construed as a representation that a search has been made, that additional items material to the examination of this application do not exist, or that any one or more of these citations constitute prior art under 35 U.S.C. 102.

The Examiner's attention is respectfully directed to the following U.S. Patents:

Publ./Pat. No.	Publ./Pat. Title	Grant Date
US 2001/0010356	THROUGH-THE-SUBSTRATE INVESTIGATION OF FLIP-CHIP IC'S	Aug. 2, 2001
US 2001/0006233	SEMICONDUCTOR DEVICES HAVING BACKSIDE PROBING CAPABILITY	Jul. 5, 2001
US 2003/0119297	METAL REDISTRIBUTION LAYER HAVING SOLDERABLE PADS AND WIRE BONDABLE PADS	Jun. 26, 2003
5,258,648	COMPOSITE FLIP CHIP SEMICONDUCTOR DEVICE WITH AN INTERPOSER HAVING TEST CONTACT FORMED ALONG ITS PERIPHERY	Nov. 2, 1993
6,081,429	TEST INTERPOSER OR USE WITH BALL GRID ARRAY PACKAGES ASSEMBLIES AND BALL GRID ARRAY PACKAGES INCLUDING SAME AND METHODS	Jun. 27, 2000
6,686,615	FLIP-CHIP TYPE SEMICONDUCTOR DEVICE FOR REDUCING SIGNAL SKEW	Feb. 3, 2004
6,307,162	INTEGRATED CIRCUIT WIRING	Oct. 23, 2001

FOREIGN DOCUMENTS

DE 195 15 591 A1 PRUUNGSANTRAG GEM Oct. 19 1995

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Patent Application

Inventor(s):	Schieck et al.	Confirmation No.:	7655
Application No.:	10/789,637	Group Art Unit:	2812
Filed:	February 27, 2004	Examiner:	Not yet assigned.
Title:	A FLIP CHIP SEMICONDUCTOR DIE INTERNAL SIGNAL ACCESS SYSTEM AND METHOD		

Form 1449

U.S. Patent Documents

Examiner Initial	No.	Publ./Patent No.	Date	Patentee	Class	Sub-class	Filing Date
	A	2001/0010356	8/2/01	Talbot et al.	250	307	2/10/01
	B	2001/0006233	7/5/01	Vallett	257	48	1/29/01
	C	2003/0119297	6/26/03	Am et al.	438	612	1/27/03
	D	5,258,648	11/2/93	Lin	257	778	11/27/92
	E	6,081,429	6/27/00	Barrett	361	767	1/20/99
	F	6,686,615	2/3/04	Cheng et al.	257	208	8/20/02
	G	6,307,162	10/2/01	Masters et al.	174	262	12/9/96
	H						
	I						
	J						
	K						

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation Yes	Translation No
	L	19515591	10/19/95	DE	H0L	23/525		X
	M							
	N							

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	R	
	S	
	T	

Examiner	Date Considered

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.